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**Embedded - System On Chip (SoC):** The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are **Embedded - System On Chip (SoC)**?

**System On Chip (SoC)** integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

Details	
Product Status	Discontinued at Digi-Key
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	256KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I <sup>2</sup> C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	1.5GHz
Primary Attributes	FPGA - 480K Logic Elements
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA, FC (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/10as048k2f35e1sg

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



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# **Key Advantages of Intel Arria 10 Devices**

Table 2. Key Advantages of the Intel Arria 10 Device Family

Advantage	Supporting Feature
Enhanced core architecture	Built on TSMC's 20 nm process technology     60% higher performance than the previous generation of mid-range FPGAs     15% higher performance than the fastest previous-generation FPGA
High-bandwidth integrated transceivers	<ul> <li>Short-reach rates up to 25.8 Gigabits per second (Gbps)</li> <li>Backplane capability up to 12.5 Gbps</li> <li>Integrated 10GBASE-KR and 40GBASE-KR4 Forward Error Correction (FEC)</li> </ul>
Improved logic integration and hard IP blocks	8-input adaptive logic module (ALM)     Up to 65.6 megabits (Mb) of embedded memory     Variable-precision digital signal processing (DSP) blocks     Fractional synthesis phase-locked loops (PLLs)     Hard PCI Express Gen3 IP blocks     Hard memory controllers and PHY up to 2,400 Megabits per second (Mbps)
Second generation hard processor system (HPS) with integrated ARM* Cortex*-A9* MPCore* processor	Tight integration of a dual-core ARM Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Intel Arria 10 system-on-a-chip (SoC)  Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric
Advanced power savings	Comprehensive set of advanced power saving features Power-optimized MultiTrack routing and core architecture Up to 40% lower power compared to previous generation of mid-range FPGAs Up to 60% lower power compared to previous generation of high-end FPGAs

# **Summary of Intel Arria 10 Features**

**Table 3.** Summary of Features for Intel Arria 10 Devices

Feature	Description
Technology	<ul> <li>TSMC's 20-nm SoC process technology</li> <li>Allows operation at a lower V<sub>CC</sub> level of 0.82 V instead of the 0.9 V standard V<sub>CC</sub> core voltage</li> </ul>
Packaging	<ul> <li>1.0 mm ball-pitch Fineline BGA packaging</li> <li>0.8 mm ball-pitch Ultra Fineline BGA packaging</li> <li>Multiple devices with identical package footprints for seamless migration between different FPGA densities</li> <li>Devices with compatible package footprints allow migration to next generation high-end Stratix® 10 devices</li> <li>RoHS, leaded<sup>(1)</sup>, and lead-free (Pb-free) options</li> </ul>
High-performance FPGA fabric	<ul> <li>Enhanced 8-input ALM with four registers</li> <li>Improved multi-track routing architecture to reduce congestion and improve compilation time</li> <li>Hierarchical core clocking architecture</li> <li>Fine-grained partial reconfiguration</li> </ul>
Internal memory blocks	M20K—20-Kb memory blocks with hard error correction code (ECC)     Memory logic array block (MLAB)—640-bit memory
	continued

<sup>(1)</sup> Contact Intel for availability.



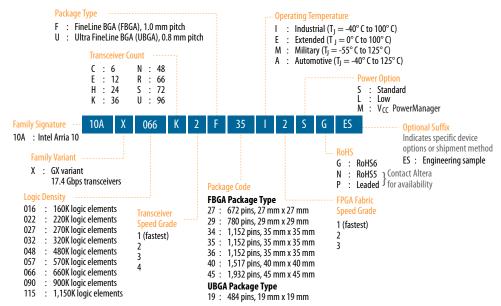
Feature		Description
Low-power serial transceivers	- Intel Arria 10 GT- Backplane support: - Intel Arria 10 GX- Intel Arria 10 GT- Extended range dow ATX transmit PLLs w Electronic Dispersion module Adaptive linear and of	—1 Gbps to 17.4 Gbps —1 Gbps to 25.8 Gbps —up to 12.5
HPS (Intel Arria 10 SX devices only)	Processor and system	Dual-core ARM Cortex-A9 MPCore processor—1.2 GHz CPU with 1.5 GHz overdrive capability  256 KB on-chip RAM and 64 KB on-chip ROM  System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers  Security features—anti-tamper, secure boot, Advanced Encryption Standard (AES) and authentication (SHA)  ARM CoreSight* JTAG debug access port, trace port, and on-chip trace storage
	External interfaces	Hard memory interface—Hard memory controller (2,400 Mbps DDR4, and 2,133 Mbps DDR3), Quad serial peripheral interface (QSPI) flash controller, NAND flash controller, direct memory access (DMA) controller, Secure Digital/MultiMediaCard (SD/MMC) controller     Communication interface— 10/100/1000 Ethernet media access control (MAC), USB On-The-GO (OTG) controllers, I²C controllers, UART 16550, serial peripheral interface (SPI), and up to 62 HPS GPIO interfaces (48 direct-share I/Os)
	Interconnects to core	High-performance ARM AMBA* AXI bus bridges that support simultaneous read and write HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa Configuration bridge that allows HPS configuration manager to configure the core logic via dedicated 32-bit configuration port FPGA-to-HPS SDRAM controller bridge—provides configuration interfaces for the multiport front end (MPFE) of the HPS SDRAM controller
Configuration	Enhanced 256-bit ad	comprehensive design protection to protect your valuable IP investments dvanced encryption standard (AES) design security with authentication obtocol (CvP) using PCIe Gen1, Gen2, or Gen3
		continued

 $<sup>^{(2)}</sup>$  Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



## **Available Options**

Figure 1. Sample Ordering Code and Available Options for Intel Arria 10 GX Devices



#### **Related Information**

Transceiver Performance for Intel Arria 10 GX/SX Devices

Provides more information about the transceiver speed grade.



#### **Maximum Resources**

Table 5. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 160, GX 220, GX 270, GX 320, and GX 480)

Resc	ource			<b>Product Line</b>		
		GX 160	GX 220	GX 270	GX 320	GX 480
Logic Elements	(LE) (K)	160	220	270	320	480
ALM		61,510	80,330	101,620	119,900	183,590
Register		246,040	321,320	406,480	479,600	734,360
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620
	MLAB	1,050	1,690	2,452	2,727	4,164
Variable-precision DSP Block		156	192	830 985		1,368
18 x 19 Multipli	er	312	384	1,660	1,970	2,736
PLL	Fractional Synthesis	6	6	8	8	12
	I/O	6	6	8	8	12
17.4 Gbps Trans	sceiver	12	12	24	24	36
GPIO (3)		288	288	384	384	492
LVDS Pair (4)		120	120 120 168 1		168	222
PCIe Hard IP Block		1	1	2	2	2
Hard Memory C	ontroller	6	6	8	8	12

 $<sup>^{(3)}</sup>$  The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>(4)</sup> Each LVDS I/O pair can be used as differential input or output.



Table 6. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 570, GX 660, GX 900, and GX 1150)

Re	source		Produc	t Line	
		GX 570	GX 660	GX 900	GX 1150
Logic Elements	s (LE) (K)	570	660	900	1,150
ALM		217,080	251,680	339,620	427,200
Register		868,320	1,006,720	1,358,480	1,708,800
Memory (Kb)	M20K	36,000	42,620	48,460	54,260
	MLAB	5,096	5,788	9,386	12,984
Variable-precision DSP Block		1,523	1,687	1,518	1,518
18 x 19 Multip	lier	3,046	3,374	3,036	3,036
PLL	Fractional Synthesis	16	16	32	32
	I/O	16	16	16	16
17.4 Gbps Trai	nsceiver	48	48	96	96
GPIO (3)		696	696	768	768
LVDS Pair (4)		324	324	384	384
PCIe Hard IP Block		2	2	4	4
Hard Memory	Controller	16	16	16	16

# **Package Plan**

# Table 7. Package Plan for Intel Arria 10 GX Devices (U19, F27, and F29)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)				F27 mm × 27 n 72-pin FBG/		F29 (29 mm × 29 mm, 780-pin FBGA)			
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	
GX 160	48	192	6	48	192	12	48	240	12	
GX 220	48	192	6	48	192	12	48	240	12	
GX 270	_	_	_	48	192	12	48	312	12	
GX 320	_	_	_	48	192	12	48	312	12	
GX 480	_	_	_	_	_	_	48	312	12	



## Table 8. Package Plan for Intel Arria 10 GX Devices (F34, F35, NF40, and KF40)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	F34 (35 mm × 35 mm, 1152-pin FBGA)		F35 (35 mm × 35 mm, 1152-pin FBGA)		KF40 (40 mm × 40 mm, 1517-pin FBGA)			NF40 (40 mm × 40 mm, 1517-pin FBGA)				
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
GX 270	48	336	24	48	336	24	_	_	_	_	_	_
GX 320	48	336	24	48	336	24	_	_	_	_	_	_
GX 480	48	444	24	48	348	36	_	_	_	_	_	-
GX 570	48	444	24	48	348	36	96	600	36	48	540	48
GX 660	48	444	24	48	348	36	96	600	36	48	540	48
GX 900	_	504	24	_	_	_	_	_	_	_	600	48
GX 1150	_	504	24	_	_	_	_	_	_	_	600	48

## Table 9. Package Plan for Intel Arria 10 GX Devices (RF40, NF45, SF45, and UF45)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	RF40 (40 mm × 40 mm, 1517-pin FBGA)		NF45 (45 mm × 45 mm) 1932-pin FBGA)		SF45 (45 mm × 45 mm) 1932-pin FBGA)			UF45 (45 mm × 45 mm) 1932-pin FBGA)				
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
GX 900	_	342	66	_	768	48	-	624	72	_	480	96
GX 1150	_	342	66	_	768	48	ı	624	72	ı	480	96

#### **Related Information**

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

#### **Intel Arria 10 GT**

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GT devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

#### **Related Information**

Intel FPGA Product Selector

Provides the latest information on Intel products.



#### **Related Information**

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

### **Intel Arria 10 SX**

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

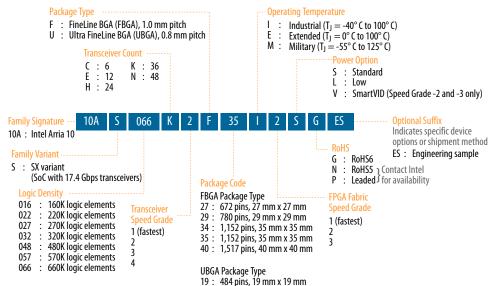
#### **Related Information**

Intel FPGA Product Selector

Provides the latest information on Intel products.

### **Available Options**

Figure 3. Sample Ordering Code and Available Options for Intel Arria 10 SX Devices



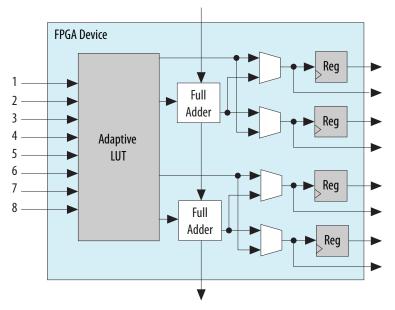
#### **Related Information**

Transceiver Performance for Intel Arria 10 GX/SX Devices

Provides more information about the transceiver speed grade.



Figure 5. ALM for Intel Arria 10 Devices



The Intel Quartus Prime software optimizes your design according to the ALM logic structure and automatically maps legacy designs into the Intel Arria 10 ALM architecture.

## **Variable-Precision DSP Block**

The Intel Arria 10 variable precision DSP blocks support fixed-point arithmetic and floating-point arithmetic.

Features for fixed-point arithmetic:

- · High-performance, power-optimized, and fully registered multiplication operations
- 18-bit and 27-bit word lengths
- Two 18 x 19 multipliers or one 27 x 27 multiplier per DSP block
- Built-in addition, subtraction, and 64-bit double accumulation register to combine multiplication results
- Cascading 19-bit or 27-bit when pre-adder is disabled and cascading 18-bit when pre-adder is used to form the tap-delay line for filtering applications
- Cascading 64-bit output bus to propagate output results from one block to the next block without external logic support
- Hard pre-adder supported in 19-bit and 27-bit modes for symmetric filters
- Internal coefficient register bank in both 18-bit and 27-bit modes for filter implementation
- 18-bit and 27-bit systolic finite impulse response (FIR) filters with distributed output adder
- Biased rounding support

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Features for floating-point arithmetic:

- A completely hardened architecture that supports multiplication, addition, subtraction, multiply-add, and multiply-subtract
- Multiplication with accumulation capability and a dynamic accumulator reset control
- Multiplication with cascade summation capability
- Multiplication with cascade subtraction capability
- Complex multiplication
- Direct vector dot product
- Systolic FIR filter

Table 15. Variable-Precision DSP Block Configurations for Intel Arria 10 Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resources
Medium precision fixed point	Two 18 x 19	1
High precision fixed or Single precision floating point	One 27 x 27	1
Fixed point FFTs	One 19 x 36 with external adder	1
Very high precision fixed point	One 36 x 36 with external adder	2
Double precision floating point	One 54 x 54 with external adder	4

#### Table 16. Resources for Fixed-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line Variable- precision DSP Block			nput and Output ons Operator	18 x 19 Multiplier Adder Sum	18 x 18 Multiplier Adder
		DSP BIOCK	18 x 19 Multiplier	27 x 27 Multiplier	Mode Mode	Summed with 36 bit Input
AIntel Arria 10	GX 160	156	312	156	156	156
GX	GX 220	192	384	192	192	192
	GX 270	830	1,660	830	830	830
	GX 320	984	1,968	984	984	984
	GX 480	1,368	2,736	1,368	1,368	1,368
	GX 570	1,523	3,046	1,523	1,523	1,523
	GX 660	1,687	3,374	1,687	1,687	1,687
	GX 900	1,518	3,036	1,518	1,518	1,518
	GX 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10 GT	GT 900	1,518	3,036	1,518	1,518	1,518
GI	GT 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10	SX 160	156	312	156	156	156
SX	SX 220	192	384	192	192	192
	SX 270	830	1,660	830	830	830
						continued



Variant	Product Line	Variable- precision DSP Block	Independent In Multiplication		18 x 19 Multiplier Adder Sum Mode	18 x 18 Multiplier Adder	
		DSP BIOCK	18 x 19 Multiplier	27 x 27 Multiplier		Summed with 36 bit Input	
	SX 320	984	1,968	984	984	984	
	SX 480	1,368	2,736	1,368	1,368	1,368	
	SX 570	1,523	3,046	1,523	1,523	1,523	
	SX 660	1,687	3,374	1,687	1,687	1,687	

Table 17. Resources for Floating-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable- precision DSP Block	Single Precision Floating-Point Multiplication Mode	Single-Precision Floating-Point Adder Mode	Single- Precision Floating-Point Multiply Accumulate Mode	Peak Giga Floating- Point Operations per Second (GFLOPs)
Intel Arria 10	GX 160	156	156	156	156	140
GX	GX 220	192	192	192	192	173
	GX 270	830	830	830	830	747
	GX 320	984	984	984	984	886
	GX 480	1,369	1,368	1,368	1,368	1,231
	GX 570	1,523	1,523	1,523	1,523	1,371
	GX 660	1,687	1,687	1,687	1,687	1,518
	GX 900	1,518	1,518	1,518	1,518	1,366
	GX 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10	GT 900	1,518	1,518	1,518	1,518	1,366
GT	GT 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10	SX 160	156	156	156	156	140
SX	SX 220	192	192	192	192	173
	SX 270	830	830	830	830	747
	SX 320	984	984	984	984	886
	SX 480	1,369	1,368	1,368	1,368	1,231
	SX 570	1,523	1,523	1,523	1,523	1,371
	SX 660	1,687	1,687	1,687	1,687	1,518

# **Embedded Memory Blocks**

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.



## **Embedded Memory Configurations for Single-port Mode**

### Table 19. Single-port Embedded Memory Configurations for Intel Arria 10 Devices

This table lists the maximum configurations supported for single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MLAB	32	x16, x18, or x20
	64 (10)	x8, x9, x10
M20K	512	x40, x32
	1K	x20, x16
	2K	x10, x8
	4K	x5, x4
	8K	x2
	16K	x1

#### **Clock Networks and PLL Clock Sources**

The clock network architecture is based on Intel's global, regional, and peripheral clock structure. This clock structure is supported by dedicated clock input pins, fractional clock synthesis PLLs, and integer I/O PLLs.

#### **Clock Networks**

The Intel Arria 10 core clock networks are capable of up to 800 MHz fabric operation across the full industrial temperature range. For the external memory interface, the clock network supports the hard memory controller with speeds up to 2,400 Mbps in a quarter-rate transfer.

To reduce power consumption, the Intel Quartus Prime software identifies all unused sections of the clock network and powers them down.

## Fractional Synthesis and I/O PLLs

Intel Arria 10 devices contain up to 32 fractional synthesis PLLs and up to 16 I/O PLLs that are available for both specific and general purpose uses in the core:

- Fractional synthesis PLLs—located in the column adjacent to the transceiver blocks
- I/O PLLs-located in each bank of the 48 I/Os

## **Fractional Synthesis PLLs**

You can use the fractional synthesis PLLs to:

- Reduce the number of oscillators that are required on your board
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

<sup>(10)</sup> Supported through software emulation and consumes additional MLAB blocks.

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The fractional synthesis PLLs support the following features:

- Reference clock frequency synthesis for transceiver CMU and Advanced Transmit (ATX) PLLs
- Clock network delay compensation
- Zero-delay buffering
- Direct transmit clocking for transceivers
- Independently configurable into two modes:
  - Conventional integer mode equivalent to the general purpose PLL
  - Enhanced fractional mode with third order delta-sigma modulation
- PLL cascading

### I/O PLLs

The integer mode I/O PLLs are located in each bank of 48 I/Os. You can use the I/O PLLs to simplify the design of external memory and high-speed LVDS interfaces.

In each I/O bank, the I/O PLLs are adjacent to the hard memory controllers and LVDS SERDES. Because these PLLs are tightly coupled with the I/Os that need to use them, it makes it easier to close timing.

You can use the I/O PLLs for general purpose applications in the core such as clock network delay compensation and zero-delay buffering.

Intel Arria 10 devices support PLL-to-PLL cascading.

## FPGA General Purpose I/O

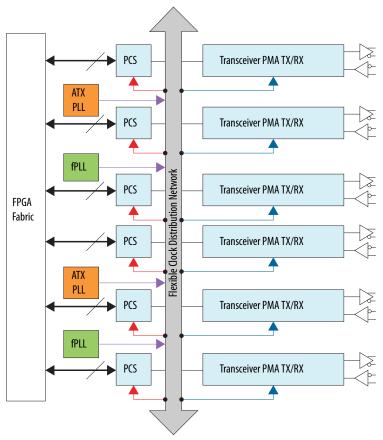
Intel Arria 10 devices offer highly configurable GPIOs. Each I/O bank contains 48 general purpose I/Os and a high-efficiency hard memory controller.

The following list describes the features of the GPIOs:

- Consist of 3 V I/Os for high-voltage application and LVDS I/Os for differential signaling
  - $-\$  Up to two 3 V I/O banks, available in some devices, that support up to 3 V I/O standards
  - LVDS I/O banks that support up to 1.8 V I/O standards
- Support a wide range of single-ended and differential I/O interfaces
- LVDS speeds up to 1.6 Gbps
- Each LVDS pair of pins has differential input and output buffers, allowing you to configure the LVDS direction for each pair.
- Programmable bus hold and weak pull-up
- Programmable differential output voltage (V<sub>OD</sub>) and programmable pre-emphasis







### **Transceiver Channels**

All transceiver channels feature a dedicated Physical Medium Attachment (PMA) and a hardened Physical Coding Sublayer (PCS).

- The PMA provides primary interfacing capabilities to physical channels.
- The PCS typically handles encoding/decoding, word alignment, and other preprocessing functions before transferring data to the FPGA core fabric.

A transceiver channel consists of a PMA and a PCS block. Most transceiver banks have 6 channels. There are some transceiver banks that contain only 3 channels.

A wide variety of bonded and non-bonded data rate configurations is possible using a highly configurable clock distribution network. Up to 80 independent transceiver data rates can be configured.

The following figures are graphical representations of top views of the silicon die, which correspond to reverse views for flip chip packages. Different Intel Arria 10 devices may have different floorplans than the ones shown in the figures.



Protocol	Data Rate (Gbps)	Transceiver IP	PCS Support
CPRI 6.0 (64B/66B)	0.6144 to 10.1376	Native PHY	Enhanced PCS
CPRI 4.2 (8B/10B)	0.6144 to 9.8304	Native PHY	Standard PCS
OBSAI RP3 v4.2	0.6144 to 6.144	Native PHY	Standard PCS
SD-SDI/HD-SDI/3G-SDI	0.143 <sup>(12)</sup> to 2.97	Native PHY	Standard PCS

#### **Related Information**

#### Intel Arria 10 Transceiver PHY User Guide

Provides more information about the supported transceiver protocols and PHY IP, the PMA architecture, and the standard, enhanced, and PCIe Gen3 PCS architecture.

## **SoC with Hard Processor System**

Each SoC device combines an FPGA fabric and a hard processor system (HPS) in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

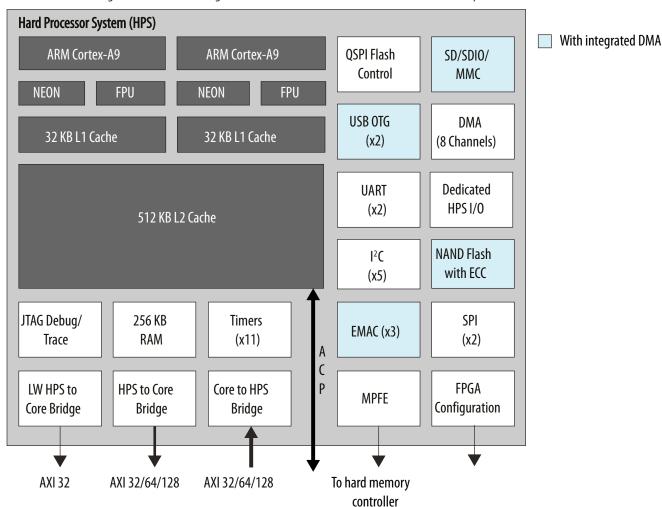
- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

<sup>(12)</sup> The 0.143 Gbps data rate is supported using oversampling of user logic that you must implement in the FPGA fabric.



Figure 9. HPS Block Diagram

This figure shows a block diagram of the HPS with the dual ARM Cortex-A9 MPCore processor.



# **Key Advantages of 20-nm HPS**

The 20-nm HPS strikes a balance between enabling maximum software compatibility with 28-nm SoCs while still improving upon the 28-nm HPS architecture. These improvements address the requirements of the next generation target markets such as wireless and wireline communications, compute and storage equipment, broadcast and military in terms of performance, memory bandwidth, connectivity via backplane and security.



Instead of placing all device functions in the FPGA fabric, you can store some functions that do not run simultaneously in external memory and load them only when required. This capability increases the effective logic density of the device, and lowers cost and power consumption.

In the Intel solution, you do not have to worry about intricate device architecture to perform a partial reconfiguration. The partial reconfiguration capability is built into the Intel Quartus Prime design software, making such time-intensive task simple.

Intel Arria 10 devices support partial reconfiguration in the following configuration options:

- Using an internal host:
  - All supported configuration modes where the FPGA has access to external memory devices such as serial and parallel flash memory.
  - Configuration via Protocol [CvP (PCIe)]
- Using an external host—passive serial (PS), fast passive parallel (FPP) x8, FPP x16, and FPP x32 I/O interface.

# **Enhanced Configuration and Configuration via Protocol**

Table 25. Configuration Schemes and Features of Intel Arria 10 Devices

Intel Arria 10 devices support 1.8 V programming voltage and several configuration schemes.

Scheme	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps) (13)	Decompression	Design Security <sup>(1</sup> 4)	Partial Reconfiguration (15)	Remote System Update
JTAG	1 bit	33	33	_	_	Yes <sup>(16)</sup>	_
Active Serial (AS) through the EPCQ-L configuration device	1 bit, 4 bits	100	400	Yes	Yes	Yes <sup>(16)</sup>	Yes
Passive serial (PS) through CPLD or external microcontroller	1 bit	100	100	Yes	Yes	Yes <sup>(16)</sup>	Parallel Flash Loader (PFL) IP core
	continued						

<sup>(13)</sup> Enabling either compression or design security features affects the maximum data rate. Refer to the Intel Arria 10 Device Datasheet for more information.

<sup>(14)</sup> Encryption and compression cannot be used simultaneously.

<sup>(15)</sup> Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Intel for support.

<sup>(16)</sup> Partial configuration can be performed only when it is configured as internal host.



Scheme	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps)	Decompression	Design Security <sup>(1</sup> 4)	Partial Reconfiguration (15)	Remote System Update
Fast passive	8 bits	100	3200	Yes	Yes	Yes <sup>(17)</sup>	PFL IP
parallel (FPP) through CPLD or	16 bits			Yes	Yes		core
external microcontroller	32 bits			Yes	Yes		
Configuration via	16 bits	100	3200	Yes	Yes	Yes <sup>(17)</sup>	_
HPS	32 bits			Yes	Yes		
Configuration via Protocol [CvP (PCIe*)]	x1, x2, x4, x8 lanes	_	8000	Yes	Yes	Yes <sup>(16)</sup>	_

You can configure Intel Arria 10 devices through PCIe using Configuration via Protocol (CvP). The Intel Arria 10 CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

#### **SEU Error Detection and Correction**

Intel Arria 10 devices offer robust and easy-to-use single-event upset (SEU) error detection and correction circuitry.

The detection and correction circuitry includes protection for Configuration RAM (CRAM) programming bits and user memories. The CRAM is protected by a continuously running CRC error detection circuit with integrated ECC that automatically corrects one or two errors and detects higher order multi-bit errors. When more than two errors occur, correction is available through reloading of the core programming file, providing a complete design refresh while the FPGA continues to operate.

The physical layout of the Intel Arria 10 CRAM array is optimized to make the majority of multi-bit upsets appear as independent single-bit or double-bit errors which are automatically corrected by the integrated CRAM ECC circuitry. In addition to the CRAM protection, the M20K memory blocks also include integrated ECC circuitry and are layout-optimized for error detection and correction. The MLAB does not have ECC.

# **Power Management**

Intel Arria 10 devices leverage the advanced 20 nm process technology, a low 0.9 V core power supply, an enhanced core architecture, and several optional power reduction techniques to reduce total power consumption by as much as 40% compared to Arria V devices and as much as 60% compared to Stratix V devices.

<sup>(13)</sup> Enabling either compression or design security features affects the maximum data rate. Refer to the Intel Arria 10 Device Datasheet for more information.

<sup>(14)</sup> Encryption and compression cannot be used simultaneously.

<sup>(15)</sup> Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Intel for support.

<sup>(17)</sup> Supported at a maximum clock rate of 100 MHz.

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September 2017  July 2017  July 2017  May 2017	2017.09.20 2017.07.13 2017.07.06 2017.05.08	<ul> <li>Removed package code 40, low static power, SmartVID, industrial, and military operating temperature support from Sample Ordering Core and Available Options for Intel Arria 10 GT Devices figure.</li> <li>Updated short reach transceiver rate for Intel Arria 10 GT devices to 25.8 Gbps.</li> <li>Removed On-Die Instrumentation — EyeQ and Jitter Margin Tool support from PMA Features of the Transceivers in Intel Arria 10 Devices table.</li> <li>Updated the maximum speed of the DDR4 external memory interface from 1,333 MHz/2,666 Mbps to 1,200 MHz/2,400 Mbps.</li> <li>Corrected the automotive temperature range in the figure showing the available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C".</li> <li>Added automotive temperature option to Intel Arria 10 GX device family.</li> </ul>
July 2017 July 2017	2017.07.13	1,333 MHz/2,666 Mbps to 1,200 MHz/2,400 Mbps.  Corrected the automotive temperature range in the figure showing the available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C".  Added automotive temperature option to Intel Arria 10 GX device family.
July 2017	2017.07.06	available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C".  Added automotive temperature option to Intel Arria 10 GX device family.
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May 2017	2017.05.08	
		<ul> <li>Corrected protocol names with "1588" to "IEEE 1588v2".</li> <li>Updated the vertical migration table to remove vertical migration between Intel Arria 10 GX and Intel Arria 10 SX device variants.</li> <li>Removed all "Preliminary" marks.</li> </ul>
March 2017	2017.03.15	<ul> <li>Removed the topic about migration from Intel Arria 10 to Intel Stratix 10 devices.</li> <li>Rebranded as Intel.</li> </ul>
October 2016	2016.10.31	<ul> <li>Removed package F36 from Intel Arria 10 GX devices.</li> <li>Updated Intel Arria 10 GT sample ordering code and maximum GX transceiver count. Intel Arria 10 GT devices are available only in the SF45 package option with a maximum of 72 transceivers.</li> </ul>
May 2016	2016.05.02	<ul> <li>Updated the FPGA Configuration and HPS Booting topic.</li> <li>Remove V<sub>CC</sub> PowerManager from the Summary of Features, Power Management and Arria 10 Device Variants and packages topics. This feature is no longer supported in Arria 10 devices.</li> <li>Removed LPDDR3 from the Memory Standards Supported by the HPS Hard Memory Controller table in the Memory Standards Supported by Intel Arria 10 Devices topic. This standard is only supported by the FPGA.</li> <li>Removed transceiver speed grade 5 from the Device Variants and Packages topic for Arria 10 GX and SX devices.</li> </ul>
February 2016	2016.02.11	<ul> <li>Changed the maximum Arria 10 GT datarate to 25.8 Gbps and the minimum datarate to 1 Gbps globally.</li> <li>Revised the state for Core clock networks in the Summary of Features topic.</li> <li>Changed the transceiver parameters in the "Summary of Features for Arria 10 Devices" table.</li> <li>Changed the transceiver parameters in the "Maximum Resource Counts for Arria 10 GT Devices" table.</li> <li>Changed the package availability for GT devices in the "Package Plan for Arria 10 GT Devices" table.</li> <li>Changed the package configurations for GT devices in the "Migration Capability Across Arria 10 Product Lines" figure.</li> <li>Changed transceiver parameters in the "Low Power Serial Transceivers" section.</li> <li>Changed the transceiver descriptions in the "Device Variants for the Arria 10 Device Family" table.</li> <li>Changed the "Sample Ordering Code and Available Options for Arria 10 GT Devices" figure.</li> <li>Changed the datarates for GT devices in the "PMA Features" section.</li> <li>Changed the datarates for GT devices in the "PCS Features" section.</li> </ul>

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Date	Version	Changes
August 2014	2014.08.18	Updated Memory (Kb) M20K maximum resources for Arria 10 GX 660 devices from 42,660 to 42,620.
		Added GPIO columns consisting of LVDS I/O Bank and 3V I/O Bank in the Package Plan table.
		Added how to use memory interface clock frequency higher than 533 MHz in the I/O vertical migration.
		Added information to clarify that RLDRAM3 support uses hard PHY with soft memory controller.
		Added variable precision DSP blocks support for floating-point arithmetic.
June 2014	2014.06.19	Updated number of dedicated I/Os in the HPS block to 17.
February 2014	2014.02.21	Updated transceiver speed grade options for GT devices in Figure 2.
February 2014	2014.02.06	Updated data rate for Arria 10 GT devices from 28.1 Gbps to 28.3 Gbps.
December 2013	2013.12.10	Updated the HPS memory standards support from LPDDR2 to LPDDR3.     Updated HPS block diagram to include dedicated HPS I/O and FPGA Configuration blocks as well as repositioned SD/SDIO/MMC, DMA, SPI and NAND Flash with ECC blocks .
December 2013	2013.12.02	Initial release.